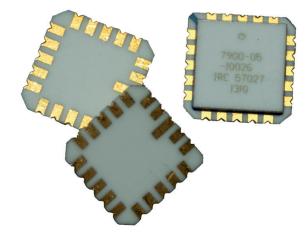


CCN Series

Features

- Qualified to DESC 87016 and 87017 military specifications
- Gold, Sn/Pb and RoHS compliant terminations available
- Ideal for all reflow soldering techniques
- Meets JEDEC standard for type 'C' package
- Custom schematics readily available
- Absolute TCR to ±15 ppm/°C



Kess All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

The IRC TaNFilm® Chip Carrier Network offers higher lead density, increased component count, lower installed resistor cost, better reliability, and is ideal for use with all surface mount solder techniques. In addition, the TaNFilm® leadless CCN provides all the unique qualities of our other TaNFilm® package configurations. Testing has demonstrated performance exceeding MIL-PRF-914 Characteristic H.

Precise state-of-the-art laser trimming provides close tolerances and tight ratios. The TaNFilm® process enables IRC to manufacture custom circuit configurations and multiple resistance values without sacrificing the tightest tolerance and tracking characteristics of precision networks. The Tantalum Nitride resistor material is passivated for environmental protection surpassing military requirements and guaranteeing exceptional ratio stability.

For applications requiring a high degree of reliability, stability, accuracy and low noise, plus the advantages of new resistor configurations, specify the IRC Leadless Chip Carrier Configuration Resistor Network.

Electrical Data

Resistance Range	10 Ω to 300K Ω			
Absolute Resistance Tolerance	To ±0.1%			
Ratio Tolerance to R1	to ±0.01%			
Power Rating @ 70°C	0.1 watt/resistor, 1.0 watt/network			
Operating Temperature Range	-55°C to +150°C			
Absolute TCR	To ±15ppm/°C			
TCR Tracking	To ±5 ppm/°C			
Noise	Less than -25 dB			
Termination Options (nickel leach barrier)	Gold 60/40 Sn/Pb 100% matte-tin			
Substrate Material	99.5% pure alumina substrate			
Construction	Epoxy overcoat (78xx) Ceramic lid (79xx)			

Custom circuits and special testing available.

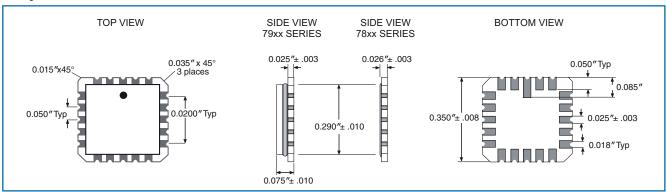


CCN Series

Manufacturing Capability Data

Circuit	Resistance Range	Available Absolute Tolerances	Available Ratio Tolerances (Ratio to R1)	Best Absolute TCR	Tracking TCR (Track to R1)
Isolated Schematics 7907/7807 7908/7808	10Ω - 24.9Ω	FGJ	FGJ DFG ±300 ppm		±50 ppm/°C
	25.0Ω - 49.9Ω	FGJ DFG ±100 ppr		±100 ppm/°C	±25 ppm/°C
	50Ω - 199Ω	DFGJ	BDFG	±50 ppm/°C	±10 ppm/°C
	200Ω - 999Ω	BDFGJ	BDFGJ BDFG ±25 ppm/°C		±5 ppm/°C
	1.0K -50.0K	BDFGJ	ABDFG	±25 ppm/°C	±5 ppm/°C
Isolated Schematic 7909/7809	10Ω - 24.9Ω	FGJ	DFG	±300 ppm/°C	±50ppm/°C
	25Ω - 74.9Ω	FGJ	DFG	±100 ppm/°C	±25 ppm/°C
	75Ω - 379Ω	DFGJ	BDFG	±50 ppm/°C	±10 ppm/°C
	380Ω - 999Ω	BDFGJ	ABDFG	±25 ppm/°C	±5 ppm/°C
	1.0ΚΩ - 100ΚΩ	BDFGJ	TQABDFG	±25 ppm/°C	±5 ppm/°C
	101ΚΩ - 250ΚΩ	BDFGJ	ABDFG	±25 ppm/°C	±5 ppm/°C
Bussed Schematic 7900/7800	10Ω - 24.9Ω	FGJ	DFG	±300 ppm/°C	±50ppm/°C
	25Ω - 74.9Ω	FGJ	DFG	±100 ppm/°C	±25ppm/°C
	75Ω - 149Ω	FGJ	BDFG	±50 ppm/°C	±10ppm/°C
	150Ω - 100ΚΩ	BDFGJ	ABDFG	±25 ppm/°C	±5ppm/°C

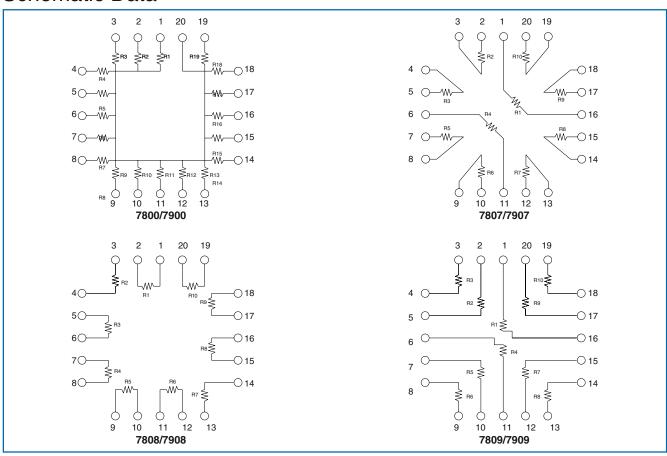
Physical Data





CCN Series

Schematic Data



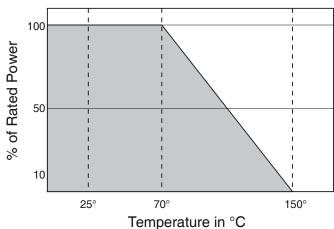
Environmental Data

Test Per MIL-PRF-914	MIL-PRF-914 Limits (∆R%)				TaNFilm [®] Test Data (△R%)	
Test Fer WIL-FRF-914	М	K	Н	V	Max	Typical
Thermal Shock and Power Conditioning	0.7	0.7	0.5	0.25	0.1	0.02
Low Temperature Operation	0.5	0.25	0.1	0.1	0.05	0.02
Short Term Overload	0.5	0.25	0.1	0.1	0.05	0.02
Resistance to Bonding Exposure	0.25	0.25	0.25	0.25	0.1	0.02
Steady State Humidity	0.5	0.5	0.5	0.2	0.1	0.03
Moisture Resistance	0.5	0.5	0.4	0.25	0.1	0.03
Shock	0.25	0.25	0.25	0.25	0.1	0.03
Vibration	0.25	0.25	0.25	0.25	0.1	0.03
Life	2.0	0.5	0.5	0.5	0.1	0.03
High Temperature Exposure	1.0	0.5	0.2	0.1	0.1	0.03
Low Temperature Storage	0.5	0.25	0.1	0.1	0.05	0.01



CCN Series

Power Derating Data



Ordering Data

